

-30V P-Channel Enhancement Mode MOSFET

Description

The AP3407AI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

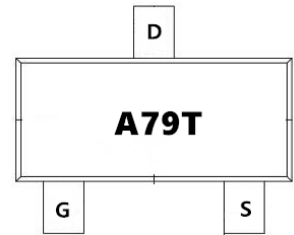
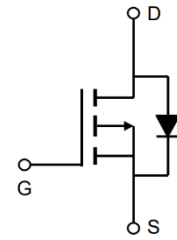
General Features

$V_{DS} = -30V$ $I_D = -4.2A$

$R_{DS(ON)} < 65m\Omega$ @ $V_{GS} = -10V$

Application

Lithium battery protection
 Wireless impact
 Mobile phone fast charging



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP3407AI	SOT-23	A79T	3000

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4.2	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.1	A
I_{DM}	Pulsed Drain Current ²	-17	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation ³	1.32	W
$P_D @ T_A = 70^\circ\text{C}$	Total Power Dissipation ³	0.84	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	125	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	95	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	80	$^\circ\text{C/W}$



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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	-36	---	V
ΔBVDSS/ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.023	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-3A	---	50	65	mΩ
		V _{GS} =-4.5V, I _D =-2A	---	65	90	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.5	V
ΔVGS(th)	V _{GS(th)} Temperature Coefficient		---	4	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	-5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =-5V, I _D =-3A	---	11	---	S
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-3A	---	6.4	9.0	nC
Q _{gs}	Gate-Source Charge		---	2.3	3.2	
Q _{gd}	Gate-Drain Charge		---	1.9	2.7	
Td(on)	Turn-On Delay Time	V _{DD} =-15V, V _{GS} =-10V, R _G =3.3Ω, I _D =-3A	---	2.8	5.6	ns
T _r	Rise Time		---	8.4	15.1	
Td(off)	Turn-Off Delay Time		---	39	78.0	
T _f	Fall Time		---	6	12.0	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	583	816	pF
C _{oss}	Output Capacitance		---	100	140	
C _{rss}	Reverse Transfer Capacitance		---	80	112	
I _s	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	-3.3	A
ISM	Pulsed Source Current ^{2,4}		---	---	-17	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _s =-1A, T _J =25°C	---	---	-1	V
t _{rr}	Reverse Recovery Time	IF=-3A, di/dt=100A/μs, T _J =25°C	---	7.8	---	nS
Q _{rr}	Reverse Recovery Charge		---	2.5	---	nC

Note : .

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

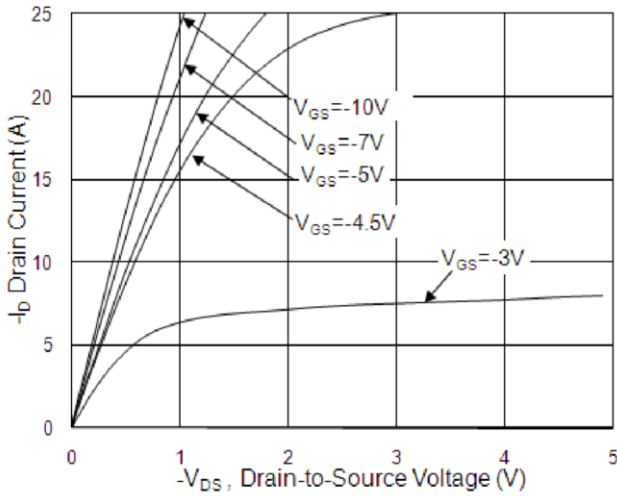


Fig.1 Typical Output Characteristics

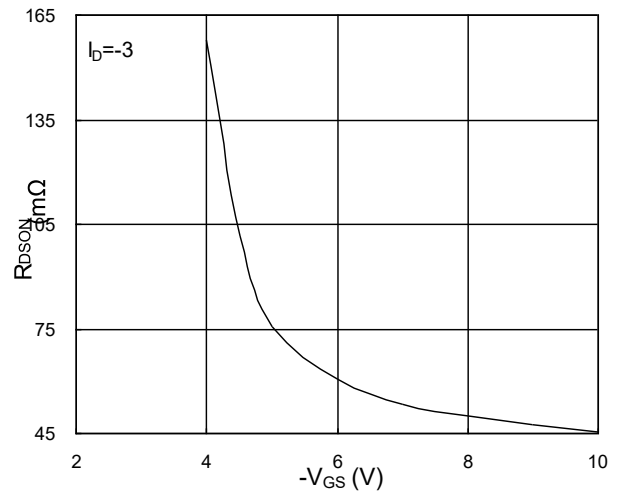


Fig.2 On-Resistance v.s Gate-Source

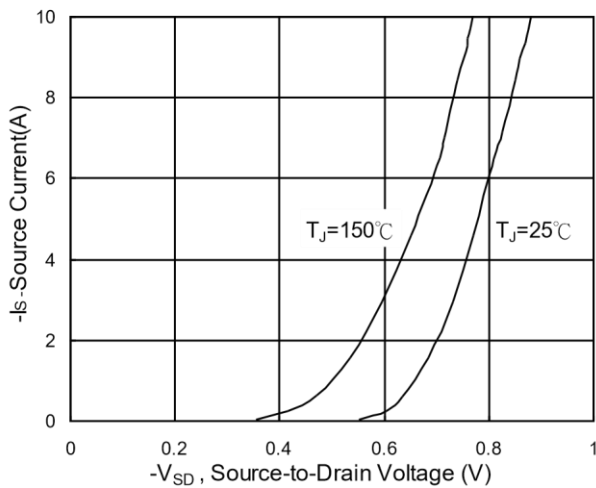


Fig.3 Forward Characteristics of Reverse

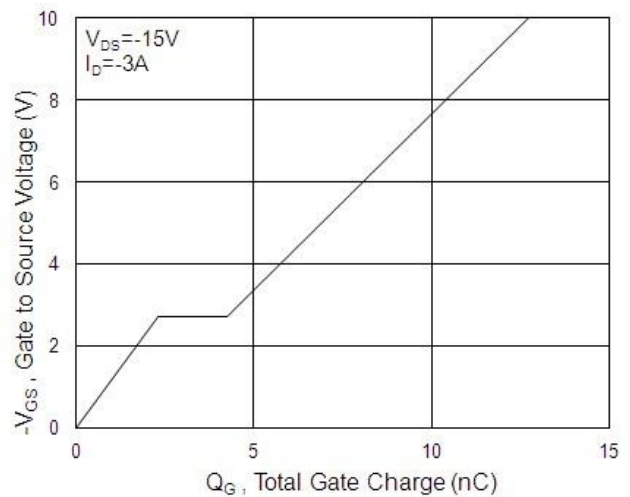


Fig.4 Gate-Charge Characteristics

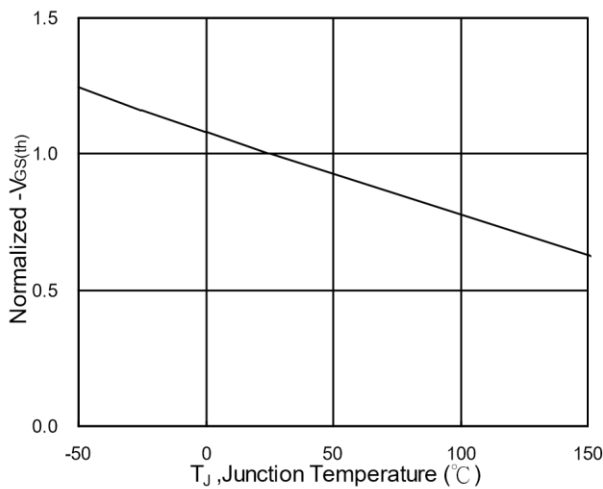


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

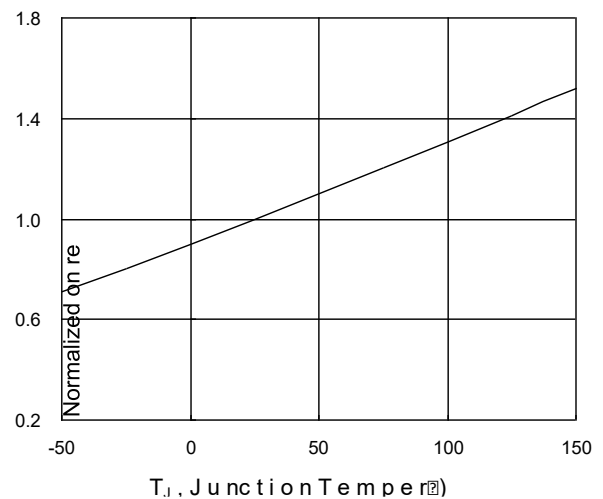


Fig.6 Normalized $R_{DS(on)}$ vs T_J



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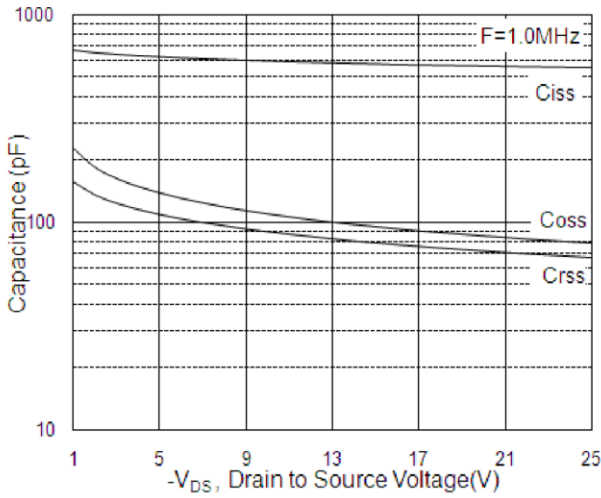


Fig.7 Capacitance

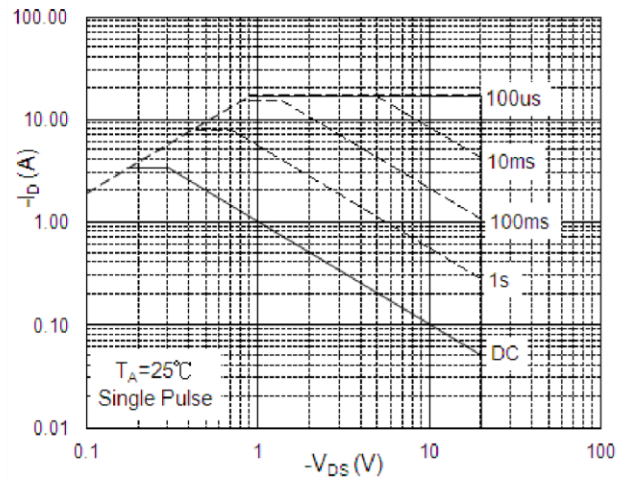


Fig.8 Safe Operating Area

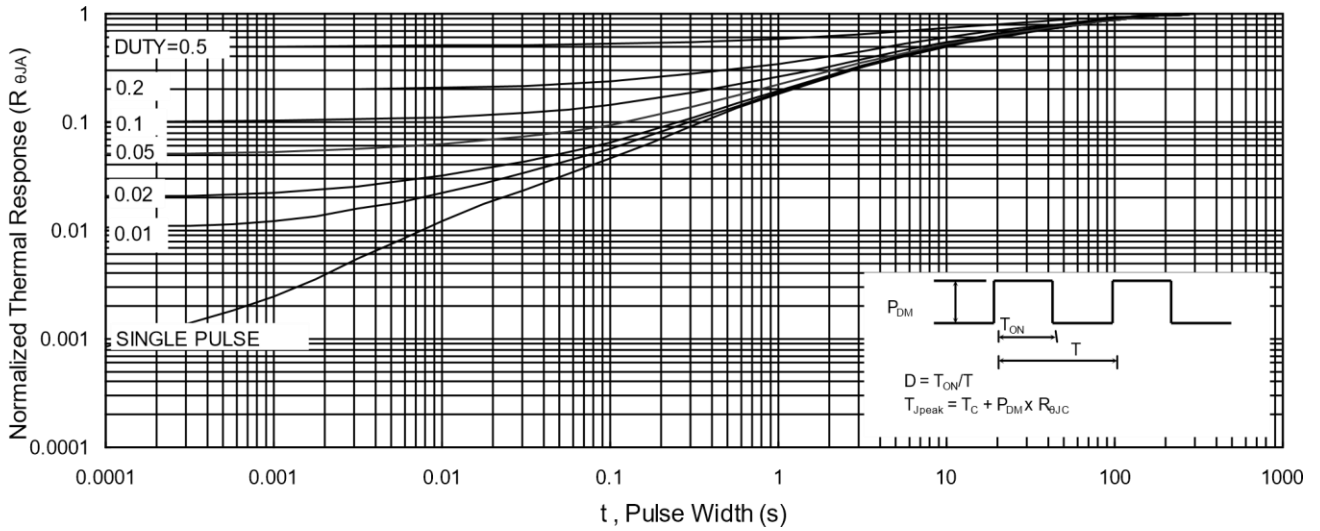


Fig.9 Normalized Maximum Transient Thermal Impedance

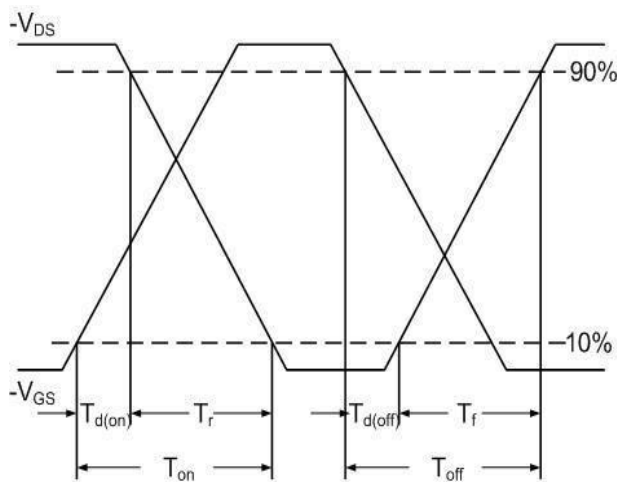


Fig.10 Switching Time Waveform

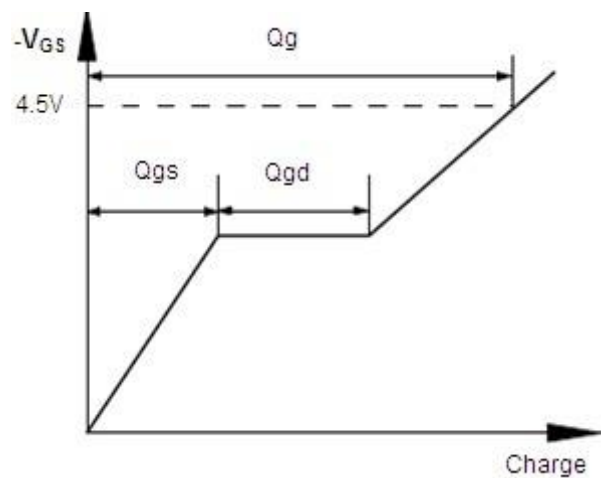
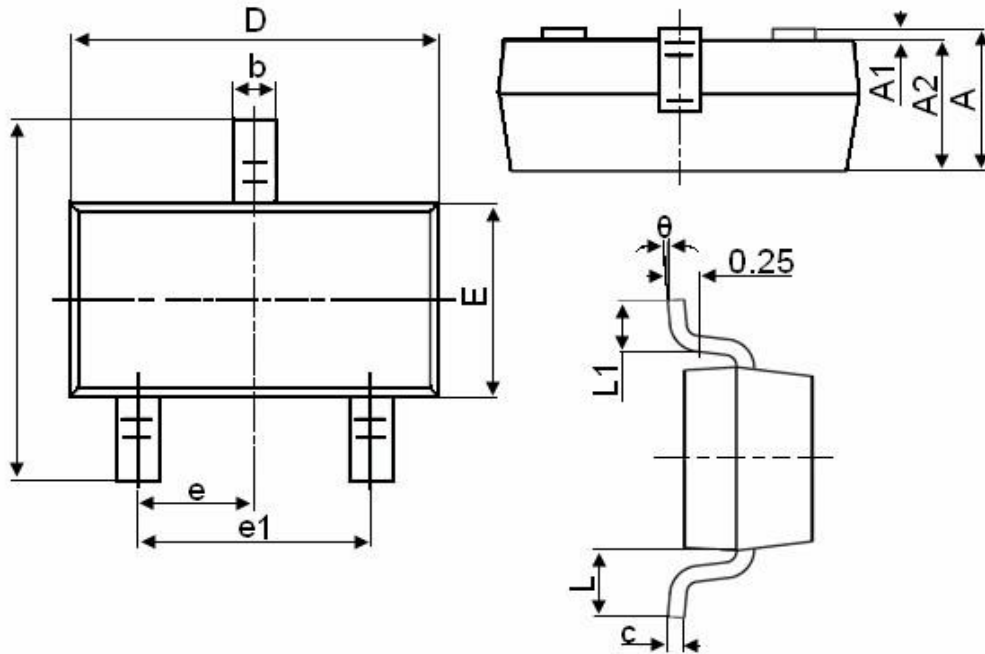


Fig.11 Gate Charge Waveform

Package Mechanical Data-SOT-23-XC


Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

-30V P-Channel Enhancement Mode MOSFET**Attention**

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